EPM12V2

Non-isolated DC-DC converter



Product features

- · Non-isolated DC-DC converter
- 3 14.4 Vdc input voltage range
- Efficiency up to 91%
- Operating ambient temperature from -40 °C to +90 °C
- Short circuit protection and remote ON/OFF function
- Programmable output voltage from 0.6 - 5.5 Vdc
- EN62368 safety approval

Engineering tools

- EPM12V2 Evaluation kit available (2 options)
- PN: EPM12V2-P-EVK (Positive logic version) Includes evaluation board with EPM12V2 sample
- PN: EPM12V2-N-EVK (Negative logic version) Includes evaluation board with EPM12V2 sample
- EPM12V2 Evaluation kit user guide

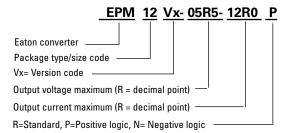
Applications

- Industrial
 - · Automation & testing equipment
 - Displays
 - Lighting
 - IoT
 - Power Supply
- Energy
 - Solar and wind inverters
 - · Battery management
- Medical
 - · Hospital & home care equipment
 - Inventory tracking
 - Diagnostics
- Telecom
 - · Networking and telecommunications
 - Infrastructure

Environmental compliance



Ordering part number





Specifications

	Parameter	Conditions		Minimum	Typical	Maximum	Unit
	Input voltage range			3	12	14.4	Vdc
	Start-up voltage	0%~100% load				3	Vdc
	VULO			2.6			V
nput		Positive DC-DC ON Open or 1.6 V \leq Von/off \leq 5.5 V DC-DC OFF Short to Gnd or 0 V \leq Von/off \leq 0.1			6 V		
	Remote ON/OFF	Negative $\begin{array}{ccc} DC\text{-}DC \ ON & Short \ to \ Gnd \ or \ O \ V \leq Von/off \leq 0 \\ DC\text{-}DC \ OFF & 1 \ V \leq Von/off \leq 5.5 \ V \end{array}$				6 V	
	Eu. :	Vo = 5 Vdc			91		%
		Vo = 3.3 Vdc			88		%
		Vo = 2.5 Vdc			86		%
	Efficiency	Vo = 1.8 Vdc			82.5		%
		Vo = 1.2 Vdc			77		%
		Vo = 0.6 Vdc			65		%
	Output voltage trim ¹			0.6		5.5	Vdc
	Minimum load			0			%
	Line regulation	LL-HL				±0.4	%
utput	Load regulation	10-100% Load				±0.2	%
	Voltage accuracy				±0.3		%
	Operating frequency	100% Load at nomin	al Vin		800		kHz
		Vo ≤ 1.2 Vdc	<u> </u>		30		mVp-p
	Ripple & noise ²	Vo > 1.2 Vdc			3% Vo		mVp-p
	Power good	Overvoltage threshol	d for PGOOD ON		116.5		%
		Overvoltage threshol			120		%
		Undervoltage thresho			91		%
					87		 %
		Undervoltage thresho	ent @VPG00D = 0.2 V		100		μA
	Operating temperature		EII	40	100	+90	°С
	Operating temperature	With derating		-40			°C
nvironment	Storage temperature			-55		+125	_
	Relative humidity				MU OTD 0000	95	%RH
	Vibration						
	01			0 1:	MIL-STD-2020		
	Short circuit protection			Contin	uous, automatic		
unction	Safety	MIL UDDVG475					
unction	Safety MTBF	MIL-HDBK217F		Contin	uous, automatic EN 62368-1	recovery	khours
unction	Safety MTBF Synchronization frequency			1132	uous, automatic		kHZ
requency	Safety MTBF Synchronization frequency High-level input voltage				uous, automatic EN 62368-1	recovery 840	kHZ V
requency	Safety MTBF Synchronization frequency High-level input voltage Low-level input voltage			1132	uous, automatic EN 62368-1 800	recovery	kHZ V V
requency	Safety MTBF Synchronization frequency High-level input voltage Low-level input voltage Input current, SYNC			1132	uous, automatic EN 62368-1 800	840 0.8	kHZ V V μ A
requency	Safety MTBF Synchronization frequency High-level input voltage Low-level input voltage Input current, SYNC Dimension			1132	800 1 (L) x 0.480 (W) x	840 0.8	kHZ V V
requency ynchronization	Safety MTBF Synchronization frequency High-level input voltage Low-level input voltage Input current, SYNC			2 0.480	1 (L) x 0.480 (W) x	840 0.8	kHZ V V μ A
requency ynchronization	Safety MTBF Synchronization frequency High-level input voltage Low-level input voltage Input current, SYNC Dimension			1132 2 0.480 (uous, automatic EN 62368-1 800 1 (L) x 0.480 (W) x 0.8 irame	840 0.8	kHZ V V μ A inches
requency ynchronization	Safety MTBF Synchronization frequency High-level input voltage Low-level input voltage Input current, SYNC Dimension Weight	range ³		1132 2 0.480 (1 (L) x 0.480 (W) x	840 0.8	kHZ V V μ A inches
requency ynchronization	Safety MTBF Synchronization frequency High-level input voltage Low-level input voltage Input current, SYNC Dimension Weight Case material			1132 2 0.480 (1 (L) x 0.480 (W) x 0.8 (ir convention	840 0.8	kHZ V V μ A inches
requency ynchronization Physical	Safety MTBF Synchronization frequency High-level input voltage Low-level input voltage Input current, SYNC Dimension Weight Case material Cooling method	EN 55032 EN61000-4-2 Air ± 8 kV		1132 2 0.480 l Open 1 Free a Class A	EN 62368-1 800 1 (L) x 0.480 (W) x 0.8 frame ir convention	840 0.8	kHZ V V μ A inches
requency ynchronization	Safety MTBF Synchronization frequency High-level input voltage Low-level input voltage Input current, SYNC Dimension Weight Case material Cooling method EMI	EN 55032 EN61000-4-2		1132 2 0.480 Open t	EN 62368-1 800 1 (L) x 0.480 (W) x 0.8 frame ir convention	840 0.8	kHZ V V μ A inches

 $[\]overline{$ 1. The output voltage range is limited by Vin. (Vout \leq Vin - 2 Vdc)

^{2.} The ripple & noise are measured with 47 μ F + 47 μ F + 0.1 μ F capacitor at 20 MHz BW.

^{3.} SYNC frequency must be greater than operating frequency, externally tie SYNC to GND if synchronization functionality not required.

^{4.} All specifications valid at nominal input voltage, full load and +25 °C after warm-up time unless otherwise stated.

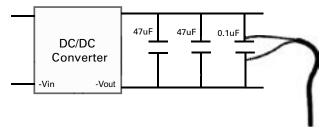
^{5.} The product information and specifications are subject to change without prior notice.

Selection guide

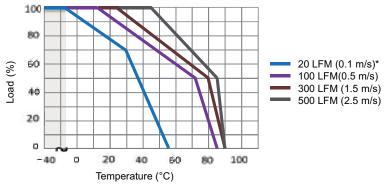
Part number	Input voltage	Output voltage	Output current @ full load	Input current @ no load	Efficiency ¹ typical	Capacitive load ² maximum	ON/OFF Logic
EPM12V2-05R5-12R0P	3 - 14.4 Vdc	0.6 - 5.5 Vdc	12 A	30 mA	91%	200 μF	Positive
EPM12V2-05R5-12R0N	3 - 14.4 Vdc	0.6 - 5.5 Vdc	12 A	30 mA	91%	200 μF	Negative

- 1. The no load input current is test by 0.6 V output.
- 2. The efficiency is test by nominal input, 5 Vout and full load @ +25 °C.
- 3. The capacitive load is test by minimum input and constant resistive load $\,$
- 4. All specifications valid at 12 V input, full load and +25 $^{\circ}\text{C}$ after warm-up time unless otherwise stated.

Measure method

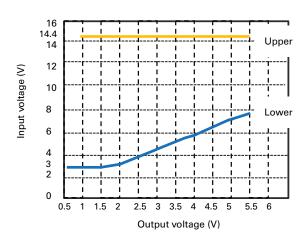


Derating curve



The derating curve was measured at 12 V input and 5 V output.

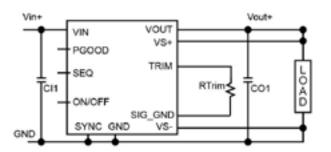
Output voltage vs. input voltage



^{*} The derating curve is at 7 V input and 5 V output

Application information

Output voltage trim



Trim resistor equation Rtrim (k Ω) = $\frac{12K}{Vo-0.6}$

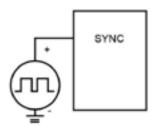
Output voltage	Calculated Rtrim (kΩ)
5.0 V	2.727
3.3 V	4.444
2.5 V	6.316
1.8 V	10
1.5 V	13.3
1.2 V	20
0.6 V	∞ (Open)

Power good

Power good monitor output. This open-drain output goes low during overcurrent, short-circuit, UVLO, overvoltage and undervoltage, overtemperature, or when the output is not regulated (such as a pre-bias output). An external pullup resistor to VDD or to an external rail is required. Included is a 20-µs deglitch filter. PGOOD pin can be connected through a pullup resistor suggested value 100 k Ω) to a source of 5 Vdc or lower.

Synchronization

The module switching frequency can be synchronized to a signal with an external frequency within a specified range. Synchronization can be done by using the external signal applied to the SYNC pin of the module, with the converter being synchronized by the rising edge of the external signal. The electrical specifications table specifies the requirements of the external SYNC signal. If the SYNC pin is not used, the module should free run at the default switching frequency. If synchronization is not being used, connect the SYNC pin to GND.



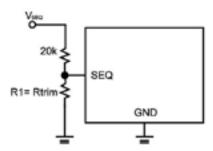
Output voltage sequencing

The SEQ pin can be used when master-slave power-supply tracking is required.

The voltage applied to the SEQ pin should be scaled down by the same ratio as used to scale the output voltage down to the reference voltage of the module. This is accomplished by an external resistive divider connected across the sequencing voltage before it is fed to the SEQ pin. The minimum recommended delay between the ON/OFF signal and the sequencing signal is 10 ms to ensure that the module output is ramped up according to the sequencing signal. This ensures that the module soft-start routine is completed before the sequencing signal is allowed to ramp up.

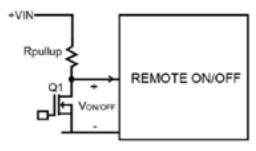
When an analog voltage is applied to the SEQ pin, the output voltage tracks this voltage until the output reaches the set-point voltage. The final value of the SEQ voltage must be set higher than the set-point voltage of the module. The output voltage follows the voltage on the SEQ pin on a one-to-one basis. By connecting multiple modules together, multiple modules can track their output voltages to the voltage applied on the SEQ pin.

To initiate simultaneous shutdown of the modules, the SEQ pin voltage is lowered in a controlled manner. The output voltage of the modules tracks the voltages below their setpoint voltages on a one-to-one basis. A valid input voltage must be maintained until the tracking and output voltages reach ground potential.



The SEQ pin can be used when master-slave power-supply tracking is required

Remote ON/OFF



Logic type active mode

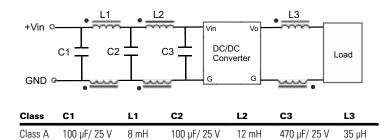
Positive Logic

DC/DC ON : Q1 OFF DC/DC OFF : Q1 ON

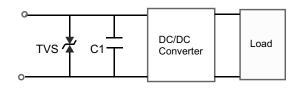
Negative Logic

DC/DC ON : Q1 ON DC/DC OFF: Q1 OFF

EMC filtering circuit



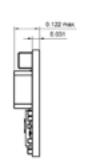
ETF and surge circuit



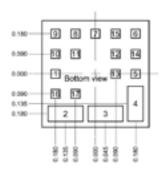
TVS	C1		
Eaton P4SMA13CA	10000 μF 25 V		

Mechanical dimension and pinning - inches







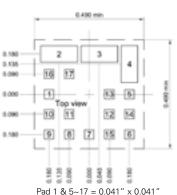


 $\begin{array}{l} \text{Projection:Third angle projection} \\ \text{Tolerance:} \pm 0.01 \\ \text{Pad } 1\&5{\sim}12 = 0.04 \times 0.04 \\ \text{Pad } 2{\sim}4 = 0.07 \times 0.157 \end{array}$

Pin	Function	Pin	Function
1	On/Off	10	PGOOD
2	Vin	11	SYNC
3	GND	12	VS-
4	Vout	13	SIG_GND
5	VS+ (Sense)	14	NC
6	TRIM	15	NC
7	GND	16	NC
8	NC	17	NC
9	SEQ		

NC = no connection

Recommended pad layout



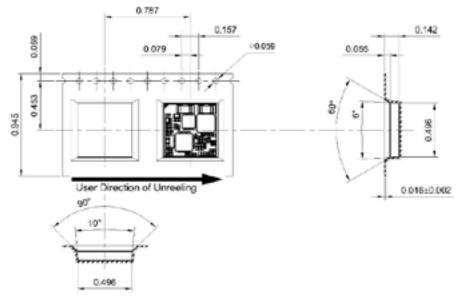
Pad 1 & $5\sim17 = 0.041" \times 0.041"$ Pad 2&4 = $0.165" \times 0.074"$

Marking

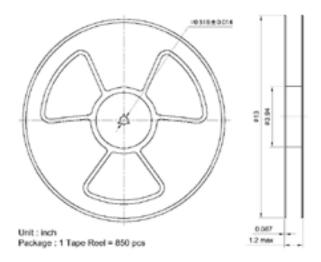


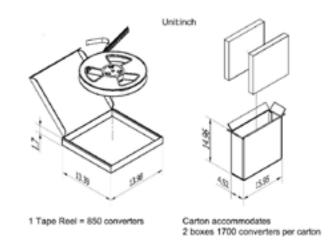
xxx= lot code

Packaging-Inches



- 1).10 sprocket hole pitch cumulative tolerance ±0.008 inch.
- 2).All dimensions meet EIA-481-2A requirements.
- 3).Component loader per 13" reel : 850 pcs.
- 4).All dimensions = ±0.004 inch.





General information

Pick and place

The 12 A open frame modules use an open frame construction and are designed for a fully automated pick and place assembly process.

MSL rating

The 12 A Open frame modules have a MSL rating of 3.

Storage and handling

The recommended storage environment and handling procedures for moisture-sensitive surface mount packages is detailed in J-STD-033 (Handling, packing, shipping and use of moisture/reflow sensitive surface mount devices).

Moisture barrier bags (MBB) with desiccant are required for MSL ratings of 3 or greater. These sealed packages should not be broken until time of use. Once the original package is broken, the floor life of the product at conditions of 30 °C and 60% relative humidity 168 hours varies according to the MSL rating (see J-STD-033). The shelf life for dry packed SMT packages will be a maximum of 12 months from the bag seal date, when stored at the following conditions: < 40 °C, < 90% relative humidity.

Post solder cleaning and drying considerations

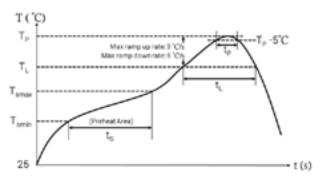
To avoid contamination on the soldering pads extra care has to be taken when handling the boards. Clean soldering surfaces do not generate as many gases when the flux reduce the metal oxides or react with contaminants during the soldering process.

Nozzle

The module weight has been kept to a minimum by using open frame construction. Variables such as nozzle size, tip style, vacuum pressure and placement speed should be considered to optimize this process.

Lead-free reflow profile

Power systems will comply with J-STD-020 (Moisture/reflow sensitivity classification for nonhermetic solid state surface mount devices) for both Pb-free solder profiles and MSL classification procedures. This standard provides a recommended forced-air-convection reflow profile based on the volume and thickness of the package. The suggested Pb-free solder paste is Sn/Ag/Cu (SAC). The recommended linear reflow profile using Sn/Ag/Cu solder is shown. Soldering outside of the recommended profile requires testing to verify results and performance.



Profile	Pb-free assembly
Average ramp-up rate $(T_{smax}$ to $T_p)$	3 °C/s max.
$ \begin{array}{l} \text{Preheat} \\ \text{Temperature Min. (T}_{\text{smin}}) \\ \text{Temperature Max. (T}_{\text{smax}}) \\ \text{T}_{\text{s}} \left(\text{T}_{\text{smin}} \text{ to T}_{\text{smax}}\right) \end{array} $	150 °C 200 °C 60-120 s
Temperature (T _p)	245°C
Time maintained above Temperature (T_L) Time (t_l)	217°C 60-150 s
Time within 5°C of the specified Peak temperature (T _p)	20-40 s
Ramp down rate (T _P to T _L)	6 °C/s max
Time 25 °C to peak temperature	8 minutes max.

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